~~TITLE OF THE INVENTION~~

ARRAY OF ELECTRODES RELIABLE, DURABLE AND ECONOMICAL AND PROCESS FOR FABRICATION THEREOF

FIELD OF THE INVENTION

This invention relates to an array of ~~electrode~~ electrodes and, more particularly, to a structure of an electrode array on an interposer between a semiconductor chip and a package and a process for fabrication thereof.

DESCRIPTION OF THE RELATED ART

An interposer connects a semiconductor chip to a package, and has electrodes opposed to a surface of the semiconductor chip where electrodes are formed. The connecting technology is used in the ball grid array and the chip size package. The ball grid array and the chip size package are abbreviated as "BGA" and "CSP", respectively.

The ball grid array consists of conductive balls arranged in matrix, and serves as an interface between a semiconductor chip and a conductive pattern on a package. The chip size package is a kind of the ball grid array package, and is smaller than the standard ball grid array package.

Figures 1A to 1L illustrate a prior art process for forming a ball grid array on a polyimide layer. The process starts with preparation of a pad 1. The pad 1 consists of an insulating organic film 1a such as polyimide and a conductive layer 1b of copper as shown in figure 1A. The insulating organic film 1a ranges from 20 microns to 50 microns thick, and the conductive pattern 1b is 10 microns to 20 microns thick.

Subsequently, the upper surface of the pad 1 is covered with a photoresist layer 2 as shown in figure 1B. The photoresist layer 2 is formed through a pre-baking after spreading photoresist solution. Alternatively ~~Otherwise,~~ a photosensitive dry film is laminated on the pad 1. The photoresist layer 2 is the negative type, and a portion exposed to light is left on the pad 2.

Subsequently, a photomask 3 is brought into physical contact with the photoresist layer 2, and the photoresist layer 2 is exposed through the photomask to light indicated by arrows in figure 1C. A pattern is transferred from the photomask 3 to the photoresist layer 2 through the contact printing technique, and a latent image is formed in the photoresist layer 2.

Subsequently, the photomask 3 is removed, and the latent image is developed. The photoresist exposed to the light is cured. However, the photoresist covered with the photomask is still soluble in developing solution. For this reason, the photoresist layer 2 is partially removed, and the photoresist layer 2 is patterned into the photoresist etching mask as shown in figure 1D.

Using the photoresist etching mask 2, the conductive layer 1b is selectively etched away, and is formed into the inverse pattern of the photoresist etching mask. The etchant contains $FeCl_3$, by way of example. Thus, conductive lands 4a and a wiring pattern 4b are formed on the polyimide film 1a as shown in figure 1E.

Subsequently, solder resist 5 is spread over the entire surface of the resultant structure, and is removed from the upper surfaces of the conductive lands

4a as shown in figure 1F. The solder resist is of synthetic resin in the polyimide system, in the epoxy system or in the phenol system.

Thereafter, solder balls 6 are formed on the conductive lands 4a, respectively. The solder balls 6 are formed of a kind of eutectic solder, and are conductive. The solder balls 6 have been prepared before the mounting, and flux has been spread over the conductive lands 4a. The solder balls 6 are ~~absorbed~~ picked up with a multi-nozzle head (not shown), and are aligned with the conductive lands 4a, respectively. The flux adheres the solder balls 6 to the conductive lands 4a, respectively. The resultant structure passes through a reflow furnace (not shown), and the solder balls 6 are bonded to the conductive lands 4a ~~in~~ nitrogen atmosphere at 200 to 250 degrees in centigrade as shown in figure 1G. The residual flux is removed from the resultant structure.

Subsequently, a pattern transfer sheet is prepared. The pattern transfer sheet has a rubber plate 7, and the rubber plate 7 is covered with ~~repellent~~ a masking agent 7a. The ~~repellant~~ masking agent is of fluorine contained polymer, fluorine contained synthetic fluid, paraffin resin or paraffin oil. The pattern transfer sheet is downwardly moved, and the ~~repellent~~ masking agent 7a is pressed against the solder balls 6 as shown in figure 1H. The rubber plate 7 is resiliently deformed, and the ~~repellent~~ masking agent 7a is brought into contact with fairly wide area. The pattern transfer sheet is upwardly moved, and the ~~repellent~~ masking agent 7a is left on the solder balls 6 as shown in figure 1I.

In this instance, the ~~repellent~~ masking agent 7a is transferred onto the solder balls 6 through the pattern transfer method. However, the ~~repellent~~ masking agent may be

printed on the solder balls 6, or the solder balls 6 may be dipped into liquid ~~repellent~~ masking agent.

Subsequently, a dispenser 8a supplies drops of liquid reinforcing resin onto gaps between the solder balls 6 as shown in figure 1J. The liquid reinforcing resin is spread over the solder resist layer 5, and covers the exposed surfaces of the solder balls 6. The reinforcing resin is solidified, and most of the exposed surfaces of the solder balls 6 are covered with the reinforcing resin layer 8 like a meniscus as shown in figure 1K.

Finally, the ~~repellent~~ masking agent 7a is removed from the solder balls 6 as shown in figure 1L. The ~~repellent~~ masking agent 7a is dissolved in solvent in this instance. The ~~repellent~~ masking agent 7a may be mechanically removed by using a lapping sheet. The solder balls 6 serve as electrodes projecting over the polyimide layer 1a. The flux enhances the wettability of the solder, and the solder resist 5 prevents the wiring pattern 4b from the solder. The reinforcing resin layer 8 fixes the solder balls 6 on the conductive lands 4a.

Japanese Patent Publication of Unexamined Application No. 10-98045 discloses a process like the prior art process described hereinbefore. The prior art process disclosed in the Japanese Patent Publication of Unexamined Application improves the resistance against thermal stress so as to prevent the resultant structure from cracks. After the packaging, the electrodes are easily separated from a package.

In the prior art process, a CSP tape or a TAB (Tape Automated Bonding) tape is available for the ball grid array. The CSP tape and the TAB tape have

been coated with the solder resist. The wiring pattern on the tape forms an electric circuit together with the integrated circuit in the semiconductor chip to be mounted thereon.

The solder resist layer 5 prevents the wiring pattern 4b from short-circuit, and the reinforcing resin layer 8 fixes the solder balls 6 to the conductive lands 4a. Thus, the prior art ball grid array is reliable and durable. However, a problem is encountered in the prior art ball grid array in the production cost. When using the CSP tape or the TAB tape already covered with the solder resist layer 5, the manufacturer suffers from a high production cost due to the high price of those tapes.

SUMMARY OF THE INVENTION

It is therefore an important object of the present invention to provide an array of electrodes, which is reliable, durable and economical.

It is also an important object of the present invention to provide a process, through which the array of electrodes is fabricated at low cost.

In accordance with one aspect of the present invention, there is provided an array of electrodes fabricated on an insulating substrate having a conductive pattern on a major surface thereof comprising plural electrodes fixed to the conductive pattern and an insulating resin layer directly covering a remaining portion of the major surface of the insulating substrate and the plural electrodes except surfaces of the plural electrodes so as to anchor the plural electrodes to the insulating substrate.

In accordance with another aspect of the present invention, there is provided a process for fabricating an array of electrodes on an insulating substrate comprising the steps of a) preparing electrodes and an insulating substrate including a conductive pattern formed on a major surface thereof and having conductive lands where the electrodes are to be fixed, b) applying conductive paste on the electrodes or the conductive lands, c) fixing the electrodes to the conductive lands by means of the conductive paste and d) covering the insulating substrate and predetermined surfaces of the electrodes with an insulating resin layer so as to anchor the electrodes to the insulating substrate.

In accordance with yet another aspect of the present invention, there is provided a process for fabricating an array of electrodes on an insulating substrate comprising the steps of a) preparing electrodes and an insulating substrate including a conductive pattern formed on a major surface thereof and having conductive lands where the electrodes are to be fixed, b) making the electrodes on the conductive lands dipped in thermosetting liquid resin spread over the insulating substrate and c) heating the resultant structure of the step b) so as to fix the electrodes to the conductive lands and solidify the thermosetting liquid resin for anchoring the electrodes to the insulating substrate.

BRIEF DESCRIPTION OF THE DRAWINGS

The features and advantages of the array of electrodes and the process will be more clearly understood from the following description taken in conjunction with the accompanying drawings in which:

Figs. 1A to 1L are schematic views showing the prior art process;

Fig. 2 is a cross sectional view showing the structure of an array of electrodes on an interposer according to the present invention;

Figs. 3A to 3J are cross sectional views showing a process for fabricating the array of electrodes on the interposer according to the present invention;

Fig. 4 is a cross sectional view showing a semiconductor device embodying the present invention;

Figs. 5A and 5B are cross sectional views showing essential steps in a process for fabricating another array of electrodes according to the present invention;

Figs. 6A to 6C are cross sectional views showing essential steps in a process for fabricating yet another array of electrodes according to the present invention;

Figs. 7A to 7C are cross sectional views showing essential steps in a process for fabricating still another array of electrodes according to the present invention;

Figs. 8A to 8D are cross sectional views showing essential steps in a process for fabricating still another array of electrodes according to the present invention; and

Fig. 9 is a plane view showing solder balls inserted into holes formed in a reinforcing resin sheet during the process shown in figures 8A to 8D.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

First Embodiment

Figure 2 illustrates an array of electrodes embodying the present invention. A solder ball 10 forms a part of the array, and serves as one of the electrodes. The other solder balls (not shown in figure 2) are similar to the solder ball 10, and description is focused on the solder ball 10, only. On an insulating organic film 11 of an interposer 12 is patterned a conductive land 13 to which the solder ball 10 is bonded by means of a ~~piece~~ bit 14 of conductive paste. Though not shown in figure 2, a conductive pattern is further formed on the insulating organic film 11, and the conductive land 13 is integral with the conductive pattern. A part of the conductive pattern connected to the conductive land 13 is electrically isolated from the other part of the conductive pattern, and, accordingly, the solder ball 10 is electrically isolated from the other solder balls. Another solder ball may be electrically connected to yet another ~~solder ball~~ conductive land.

The solder ball 10 is formed of eutectic solder, and serves as a bump. Other conductive materials are available for the bump. The bump may be implemented by a high-temperature solder ball, a gold ball or a copper ball. The insulating organic layer 11 is, by way of example, formed from a polyimide film, and the conductive land 13 is formed of copper. The ~~piece~~ bit 14 of conductive paste is formed of silver paste, gold paste or solder paste. The solder paste contains solder powder dispersed in flux. When the solder paste is selected, the flux ~~is to~~ should be removed from the array of electrodes. However, there

is a kind of paste, which allows the manufacturer to bond the solder ball 10 to the conductive land 13 without ~~the~~ cleaning.

The solder ball 10 is to be bonded to a printed circuit board 16. For this reason, the solder ball 10 is covered with a reinforcing resin layer 16 except for the upper portion to be bonded to the printed circuit board 15. The exposed upper surface of the insulating organic film 11, the conductive land 13, a conductive pattern (not shown) on the insulating organic film 11 and the ~~piece~~ bit 14 of conductive paste are ~~perfectly~~ completely covered with the reinforcing resin layer 16. The reinforcing resin layer 16 anchors the solder ball 10 to the insulating organic film 11, and does not allow the solder ball 10 to move on the conductive land 13. Although the piece 14 of conductive paste bonds the solder ball 10 to the conductive land 13, the reinforcing resin layer 16 enhances the stability of the solder ball 10 on the conductive land 13. The reinforcing resin layer 16 is insulating, and ~~prevents~~ protects the conductive pattern (not shown) from short-circuit. Thus, the reinforcing resin layer 16 not only enhances the stability of the solder ball 10 but also ~~prevents~~ protects the conductive patter from short-circuit.

Various kinds of synthetic resin are available for the reinforcing resin layer 16. These kinds of synthetic resin may belong to the polyimide system, the epoxy system, the phenol system, the acrylic system and the silicone system. When the manufacturer selects the synthetic resin, the material of the insulating organic film is taken into account. In this instance, the insulating organic film 11 is formed of polyimide resin, it is appropriate to use the syn-

thetic resin in the polyimide system, the epoxy system, the phenol system or the silicone system. The bonding strength is ~~largest~~ greatest between the insulating organic film 11 of polyimide resin and the synthetic resin in the polyimide system, and is decreased toward the synthetic resin in the silicone system. However, if the insulating organic film 11 is formed of epoxy resin or phenol resin, the synthetic resin is selected from the epoxy system, the phenol system, the acrylic system or the polyimide system. The bonding strength is ~~largest~~ greatest between the insulating organic film of the epoxy resin/ phenol resin and the synthetic resin in the epoxy system, and is decreased toward the synthetic resin in the polyimide system.

Description is hereinbelow made on a process for fabricating the array of electrodes on the interposer 12 with reference to figures 3A to 3J. The process starts with preparation of a pad 18. The pad 18 has the insulating organic film 11 of polyimide and a copper layer 19 laminated on the insulating organic film 11 as shown in figure 3A. In this instance, the insulating organic film 11 is 20 microns to 50 microns thick, and the copper layer 19 is 10 microns to 20 microns thick.

Subsequently, the pad 18 is covered with a photo-resist layer 20 as shown in figure 3B. Photo-resist is spread over the copper layer 18, and, thereafter, the photo-resist is pre-baked. Otherwise, a photo-sensitive dry film is bonded onto the copper layer 19. In this instance, the photo-resist layer 20 is of ~~he~~ the negative type.

A photomask 21 is provided over the photo-resist layer 20, and the photo-resist layer 20 is radiated with light through the photomask 21 as shown in figure 3C. The light is indicated by arrows. The photo-resist exposed to the light is polymerized, and is cured. However, the photo-resist under the photomask 21 remains soluble. As a result, the mask pattern is transferred to the photo-resist layer 20, and a latent image is formed therein. The photo-resist layer 20 is selectively dissolved in developing solution as shown in figure 3D, and the latent image is developed. The remaining photo-resist layer 20 serves as an etching mask.

Subsequently, the copper layer 19 is selectively etched. The photo-resist etching mask exposes parts of the copper layer 19 to etchant, and the etchant removes the exposed parts of the copper layer 19. In this instance, the etchant contains $FeCl_3$. As a result, the conductive lands 13 and a conductive pattern 17 are left on the insulating organic film 11 as shown in figure 3E. The conductive pattern 17 is integral with the conductive lands 13.

Subsequently, the silver paste 23 is printed on the conductive lands 13. A vacuum clamper 22 ~~absorbs~~ pick up the solder balls 10. Vacuum passages 22a are formed in the vacuum clamper 22, and are open to the lower surface of the vacuum clamper 22. The vacuum clamper 22 carries the solder balls 10 to the conductive lands 13, and aligns the solder balls 10 with the conductive lands 13, respectively, as shown in figure 3F. The silver paste 23 is thermally cured so as to bond the solder balls 10 to the conductive lands 13, respectively, as shown in figure 3G. Thus, the solder balls 10 are not reflowed, and,

accordingly, ~~any~~ no flux is required for the solder balls 10. The silver paste 23 is conductive, and the solder balls 10 are electrically connected to the conductive lands 13, respectively.

Subsequently, a pattern transfer sheet is prepared, and is moved over the solder balls 10 as shown in figure 3H. ~~Repellent~~ Masking agent 24 is spread over the lower surface of a rubber plate 25. The ~~repellent~~ masking agent 24 is of fluorine contained polymer, fluorine contained synthetic fluid, paraffin resin, paraffin oil, silicone resin or silicone oil. The solder balls 10 may be coated with the ~~repellent~~ masking agent through a printing or dipping.

The ~~repellent~~ masking agent 24 is pressed against the solder balls 10. The rubber plate 25 is resiliently deformed along the surfaces of the solder balls 10, and brings the ~~repellent~~ masking agent 24 to the upper portions of the solder balls 10. Thus, the upper portions of the solder balls 10 are coated with ~~repellent~~ masking agent layers 24. The heating temperature is 120 degrees to 150 degrees in centigrade.

Subsequently, low-viscous liquid resin 16 is dropped from a dispenser 26 to between the solder balls 10 as shown in figure 3I. The ~~repellent~~ masking agent 24 ~~prevents~~ protects the upper portions of the solder balls 10 from the liquid resin, and the liquid resin is spread over the remaining surface of the resultant structure. The exposed surface of the insulating organic film 11, the conductive pattern 17 and the exposed surfaces of the solder balls 10 are covered with the reinforcing resin layer 16 like a meniscus. The reinforcing resin layer enhances the stability of the solder balls 10 on the conductive lands 13.

The liquid resin layer 16 is solidified, and, thereafter, the ~~repellent~~ masking agent 24 is removed from the solder balls 10. When the reinforcing resin belongs to the epoxy system or the phenol system, the liquid resin 16 is thermally cured at 100 degrees to 150 degrees in centigrade. If the reinforcing resin belongs to the polyimide system, the liquid resin 16 is thermally cured at 100 degrees to 250 degrees in centigrade. The ~~repellent~~ masking agent 24 is chemically or mechanically removed. When the ~~repellent~~ masking agent 24 is chemically removed, appropriate solvent is used. A lapping sheet may be used in the mechanical removal. Thus, the upper portions of the solder balls 10 are exposed, again. The resultant structure is shown in figure 3J.

The array of electrodes on the interposer 12 is assembled with a semiconductor chip 28 as shown in figure 4. Circuits components are integrated in the semiconductor chip 28, and form an integrated circuit. The array of electrodes on the interposer 12 and the semiconductor chip 28 as a whole constitute a semiconductor device. The semiconductor chip 28 has a reverse surface 28a, and electrodes are formed on the reverse surface 28a. Small bubbles represent the electrodes. Though not shown in figure 4, the conductive pattern 17 passes through via holes formed in the insulating organic film 11, and extends on the reverse surface. The interposer 12 is fixed to the semiconductor chip by means of adhesive compound 27, and the electrodes of the semiconductor chip 28 are connected to the conductive pattern on the reverse surface of the insulating organic film 11. Thus, the integrated circuit is electrically connected through the electrodes and the conductive pattern 17 to the

solder balls 10. The semiconductor device 29 is, by way of example, mounted on a circuit board (not shown), and forms a part of an electronic system.

As will be understood from the foregoing description, the reinforcing resin layer 16 enhances the stability of the solder balls 10 on the conductive lands 23, and offers the electric insulation to the conductive pattern 17. ~~Any~~ no solder resist is not required for the array of electrodes on the interposer 12, nor any CPS/ TAB tape already covered with the solder resist. For this reason, the manufacturer fabricates the array of electrodes on the interposer 12 at a low cost.

Moreover, the solder balls 10 are fixed to the conductive lands 13 by means of the conductive paste 23. The solder balls 10 are ~~never~~ not reflowed, nor any flux is required. This means that the process does not ~~contain~~ require the cleaning step for residual flux. Thus, the process according to the present invention is simpler than the prior art process, and the simple process ~~makes~~ permits the manufacturer to reduce the production cost of the semiconductor device.

Second Embodiment

Another array of electrodes embodying the present invention is similar to the first embodiment except the connection between the solder balls 10 and the conductive lands 13. For this reason, description is focused on different steps of a process for fabricating the array of electrodes on an interposer. In the following description and figures 5A and 5B, components of the second embodiment are labeled with the same references designating corresponding components of the first embodiment without detailed description.

In the process for the second embodiment, solder paste is used for connecting the solder balls 10 to the conductive lands 13. Upon completion of the pattering step for the conductive lands 13 and the conductive pattern 17, the solder balls 10 are clamped by the vacuum picked up ~~clamper~~ 22, and the solder paste is adhered to lower portions of solder balls 10. The vacuum clamper 22 carries the solder balls onto the conductive lands 13, and puts the solder balls 10 on the conductive lands 13 as shown in figure 5A. The solder paste is viscous, and keeps the solder balls 10 on the conductive lands 13. The solder paste may be printed on the conductive lands 13 before the solder balls 10 are brought into contact with the conductive lands 13.

Subsequently, the resultant structure passes through a reflow furnace (not shown). Nitrogen atmosphere at 200 degrees to 250 degrees ~~to~~ centigrade is created in the reflow furnace, and the solder powder ~~power~~ in the paste is melted. The melted solder is cooled, and the solder balls 10 are fixed to the conductive lands 13 by means of meniscus-like solder pieces 30, respectively, (see figure 5B). The remaining flux is removed from the resultant structure. If the solder paste is of the type free not requiring ~~from the~~ cleaning, the process sequence is simple. After the step of fixing the solder balls 10 to the conductive lands 13, the process sequence returns to the step shown in figure 3H.

It is appropriate to use the solder powder lower in melting point than the solder balls 10. A belt furnace is available for the reflow, and the solder powder is melted around 230 degrees in centigrade. The reflow may be carried out in any kind of non-oxidizing atmosphere.

The solder paste is desirable rather than the eutectic solder. The solder resist is indispensable to the eutectic solder, because the eutectic solder flows out of the conductive lands 13. When the solder paste is melted, the melted solder is adhered between the conductive lands 13 and the solder balls 10 like a meniscus, and does not flow out of the conductive lands 13. Thus, the solder paste allows the manufacturer to eliminate the solder resist from the array of electrodes on the interposer 12. No ~~Any~~ CSP/ TAB tape coated with the solder resist is ~~not~~ required for the array of electrodes according to the present invention. As a result, only the reinforcing resin layer 16 is required for the array of electrodes fabricated on the interposer 12, and the manufacturer can fabricate the array of electrodes at a low cost.

Third Embodiment

Yet another array of electrodes embodying the present invention is similar in structure to the first and second embodiments. However, a process for the third embodiment is different from those for the first and second embodiments. In the processes for the first embodiment and the second embodiment, the solder balls 10 are firstly fixed onto the conductive lands 13, and, thereafter, the resultant structure is partially covered with the reinforcing resin layer 16 through the thermal curing. The process for the third embodiment concurrently carries out the fixing step and the thermal curing.

The process sequence is similar to the process for the first embodiment until the step shown in figure 3E. Figures 6A to 6C illustrate essential steps after the step shown in figure 3E.

The dispenser 26 supplies drops of liquid resin 16 onto the insulating organic film 11, and the liquid resin is spread over the entire surface. The exposed area of the insulating organic film 11, the conductive lands 13 and the conductive pattern 17 are covered with the liquid resin layer 16 as shown in figure 6A. The liquid resin may be printed on the insulating organic film 11. Flux may be spread on the conductive lands 13 before spreading the liquid resin.

Subsequently, the solder balls 10 are picked up ~~clamped~~ with the vacuum clamper 22, and are pressed against the conductive lands 13. The solder balls 10 push away the liquid resin 16, and are brought into contact with the conductive lands 13. The solder balls 10 get the lower portions wet, and make the liquid resin layer 16 meniscus. The solder balls 10 are continuously pressed against the conductive lands 13, and supersonic vibrations are applied to the solder balls 10. The friction between the solder balls 10 and the conductive lands 13 fixes ~~makes~~ the solder balls 10 ~~bonded~~ to the conductive lands 13, respectively as shown in figure 6B. For this reason, it is desirable to use low-viscous liquid resin.

The vacuum clamper 22 releases the solder balls 10, and the liquid resin is solidified. In this instance, the resultant structure is placed in a ~~into~~ high-temperature nitrogen atmosphere, and the liquid resin is baked and solidified. As a result, the power portions of the solder balls 10, the exposed areas of the conductive lands 13, the conductive pattern 17 and the exposed area of the insulating organic film 11 are covered with the reinforcing resin layer 16 as

shown in figure 6C. When the liquid resin belongs to the polyimide system, the nitrogen atmosphere is heated to 150 degrees to 250 degrees in centigrade.

While the high-temperature nitrogen atmosphere is baking the liquid resin, the solder balls 10 are strongly fixed to the conductive lands 13. The reinforcing resin layer 16 enhances the stability of the solder balls 10 on the conductive lands 13.

If the solder balls 10 are, by way of example, 0.8 millimeter in diameter, the liquid resin 16 tends to reach upper portions of the solder balls 10, and the reinforcing resin may be chemically or mechanically removed from the upper portions of the solder balls 10 by using solvent or a lapping sheet.

As will be understood from the foregoing description, the solder balls 10 are temporarily fixed to the conductive lands 13 by using the supersonic vibrations after covering the entire surface with the liquid resin 16, and are strongly fixed to the conductive lands 13 during the solidification of the liquid resin 16. The reinforcing resin layer 16 prevents the melted solder ~~to~~ ~~flow~~ from flowing out of the conductive lands 13. For this reason, the array of electrodes fabricated on the interposer 12 does not require any solder resist layer, and is fabricated at low cost by virtue of the elimination of solder resist layer.

Fourth Embodiment

Still another array of electrodes embodying the present invention is similarly fabricated on the interposer 12. However, the solder balls 10 are placed on the conductive lands 13 before covering the conductive pattern with the liquid resin. A fabrication process for the fourth embodiment is similar to the

process for the first embodiment until the step shown in figure 3E, and the remaining steps are described with reference to figures 7A to 7C.

The solder balls 10 are ~~clamped~~ picked up with the vacuum clamper 22, and lower portions of the solder balls 10 are coated with flux 31. The flux is of the type ~~free from the~~ not requiring cleaning, and, accordingly, does not deteriorate the array of electrodes fabricated on the interposer 12. The solder balls 10 are aligned with the conductive lands 13, and are put on the conductive lands 13, respectively. The flux 31 is dried, and the solder balls 10 are temporarily fixed to the conductive lands 13 as shown in figure 7A. The flux 31 may be printed on the conductive lands 13 before the step shown in figure 7A.

Subsequently, liquid resin 16 is dropped from the dispenser 26 onto the insulating organic film 11. The liquid resin 16 is spread over the insulating organic film 11, and lower portions of the solder balls 10, the conductive pattern 17 and exposed area of the insulating organic film 11 are covered with the liquid resin 16 as shown in figure 7B. The liquid resin 16 rises around the solder balls 10 like a meniscus, and the dry flux 31 ~~presents~~ protects the conductive lands 13 from the liquid resin 16.

Subsequently, the resultant structure is placed in nitrogen atmosphere at 200 degrees to 250 degrees ~~in~~ centigrade. The liquid resin is thermally cured, and the resultant structure is covered with the reinforcing resin layer 16 except the upper portions of the solder balls 10. While the high-temperature nitrogen atmosphere is solidifying the liquid resin 16, the solder balls 10 are partially melted, and are strongly bonded to the conductive lands 13, respec-

tively as shown in figure 7C. The reinforcing resin layer 16 enhances the stability of the solder balls 10 on the conductive lands 13. The reinforcing resin layer 16 does not allow the melted solder to flow out of the conductive lands 13, and ~~any~~ no solder resist layer is required for the array of electrodes fabricated on the interposer 12. This results in reduction in production cost.

If the reinforcing resin reaches upper portions of the solder balls 10, the manufacturer chemically or mechanically removes the reinforcing resin from the upper portions of the solder balls 10. The array of electrodes and the fabrication process implementing the fourth embodiment achieve all the advantages of the first embodiment.

<u>Fifth Embodiment</u>

Still another array of electrodes embodying the present invention is fabricated on the interposer 12 through a process shown in figures 8A to 8D. The process is similar to the process for the first embodiment until the step shown in figure 3E. Figures 8A to 8D illustrate the remaining steps of the process after the step shown in figure 3E.

A reinforcing resin sheet 32 is prepared. The reinforcing resin sheet 32 is thermally fusible and, thereafter, curable. Epoxy powder or other synthetic resin powder available for a molding is solidified. The reinforcing resin sheet 32 has the thickness equal to a third of the diameter of the solder balls 10. Through-holes 33 are formed in the reinforcing resin sheet 32, and are lain out on the pattern of the conductive lands 13. The diameter of the through-

holes 33 is approximately equal to or slightly less than the diameter of the solder balls 10.

The solder balls 10 are ~~clamped~~ picked up with the vacuum clamper 22, and are aligned with the through-holes 33, respectively as shown in figure 8A. The vacuum clamper 22 is downwardly moved, and releases the solder balls 10. The solder balls 10 are snugly received in the through-holes 33 as shown in figure 8B and figure 9.

Subsequently, the reinforcing resin sheet 32 is moved to the predetermined position over the insulating organic film 11, and lower portions of the solder balls 10 are coated with the flux 31. The flux 31 is of the type ~~free from the~~ not requiring cleaning. When the reinforcing resin sheet 32 reaches the predetermined position, the solder balls 10 are automatically aligned with the conductive lands 13, respectively. It is not necessary to align the individual solder balls 10 with the associated conductive lands 13. Thus, the alignment work is speedy. The reinforcing resin sheet 32 is downwardly moved as shown in figure 8C, and the solder balls 10 coated with the flux 31 are pressed against the conductive lands 13. The flux 31 is dried, and the solder balls 10 are fixed to the conductive lands 13 by using the conductive paste 14 such as the silver paste or the solder paste. The flux 31 may be replaced with flux to be ~~learned~~ applied thereafter.

When the solder balls 10 are fixed to the conductive lands 13, the reinforcing resin sheet 32 is slightly spaced from the insulating organic film 11. The reinforcing resin sheet 32 is heated to 100 degrees to 150 degrees ~~in~~ cen-

tigrade in nitrogen atmosphere or vacuum. Then, the reinforcing resin sheet is melted, and is spread over the insulating organic film 11. The solder balls 10 make the melted resin meniscus therearound, and upper portions of the solder balls 10 are uncovered with the melted resin 16. The flux 31 protects ~~prevents~~ the conductive lands 13 from the melted resin 16.

The melted resin is dried, and is solidified. As a result, the insulating organic film 11 is covered with the reinforcing resin layer 16 as shown in figure 8D. If the reinforcing resin is left on the upper portions of the solder balls 10, it is chemically or mechanically removed from the upper portions. The reinforcing resin layer 16 anchors the solder balls 10 to the insulating organic film 11, and enhances the stability of the solder balls 10 on the conductive lands 13. No ~~Any~~ solder flows out of the conductive lands 13, and no ~~any~~ solder resist is required. For this reason, the array of electrodes is fabricated on the interposer 12 at low cost.

As will be understood from the foregoing description, the reinforcing resin sheet 32 enhances the productivity by virtue of the concurrent alignment work for the solder balls 10. The conductive paste fixes the solder balls 10 to the conductive lands 13 without reflow, and no ~~any~~ solder resist is required. Thus, the array of electrodes is fabricated on the interposer 12 at low cost.

Although particular embodiments of the present invention have been shown and described, it will be apparent to those skilled in the art that various changes and modifications may be made without departing from the spirit and scope of the present invention.

For example, the conductive paste may be spread on the solder balls 10. A process according to the present invention may not include the step of covering the upper portions of the solder balls 10 with the ~~repellent~~ masking agent. When the solder balls are large, the liquid resin does not reach the upper portions of the solder balls 10, and the manufacturer can eliminate the step from the process.